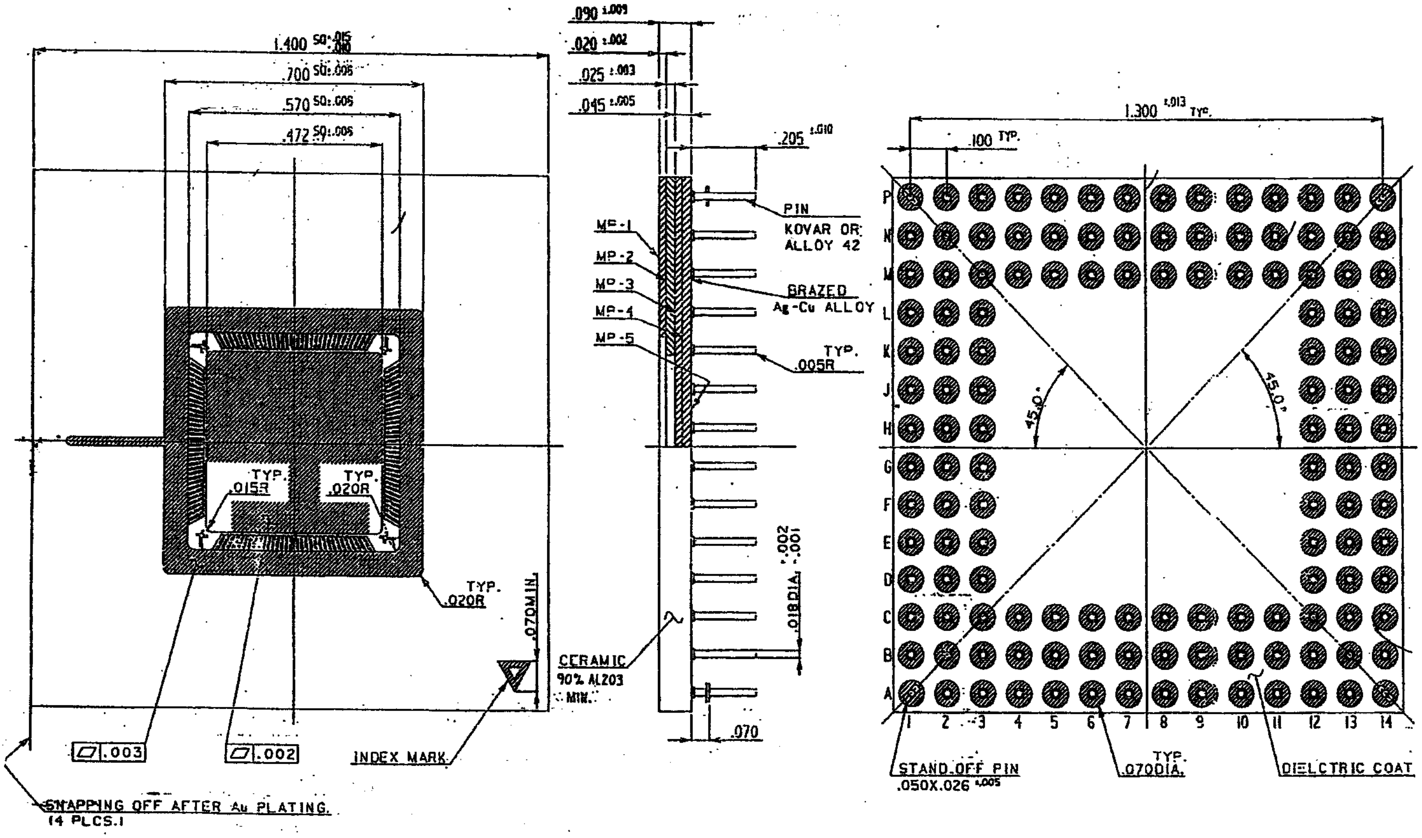
SSM P/N CPG13226



NOTES: UNLESS OTHERWISE SPECIFIED.

1. GOLD PLATING THICKNESS FOR LEADS 60-150 MICRO IN. Au. OTHERS 60-225 MICRO IN. Au. AND NICKEL 50-350 MICRO IN. Au. MIN.
2. SEAL RING AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AREA AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE: B/F NO. 1,16,17,34,49,50,67,82,83,100,
   115,116 .... 200m OHMS MAX.
   THE OTHERS .... 1500m OHMS MAX.
6. CORRESPONDING VENDOR: KYOCERA : KD-P88069.

2-17-88	1	REVISE B/F LAYOUT		RJM	
2-17-87	0	INITIAL RELEASE		JAE	H. NGUYEN
DATE	REV.	REVISION HISTORY	ECN NO.	DRN. BY	CHK. BY

UNLESS OTHERWISE SPECIFIED
DIMENSIONAL TOLERANCES

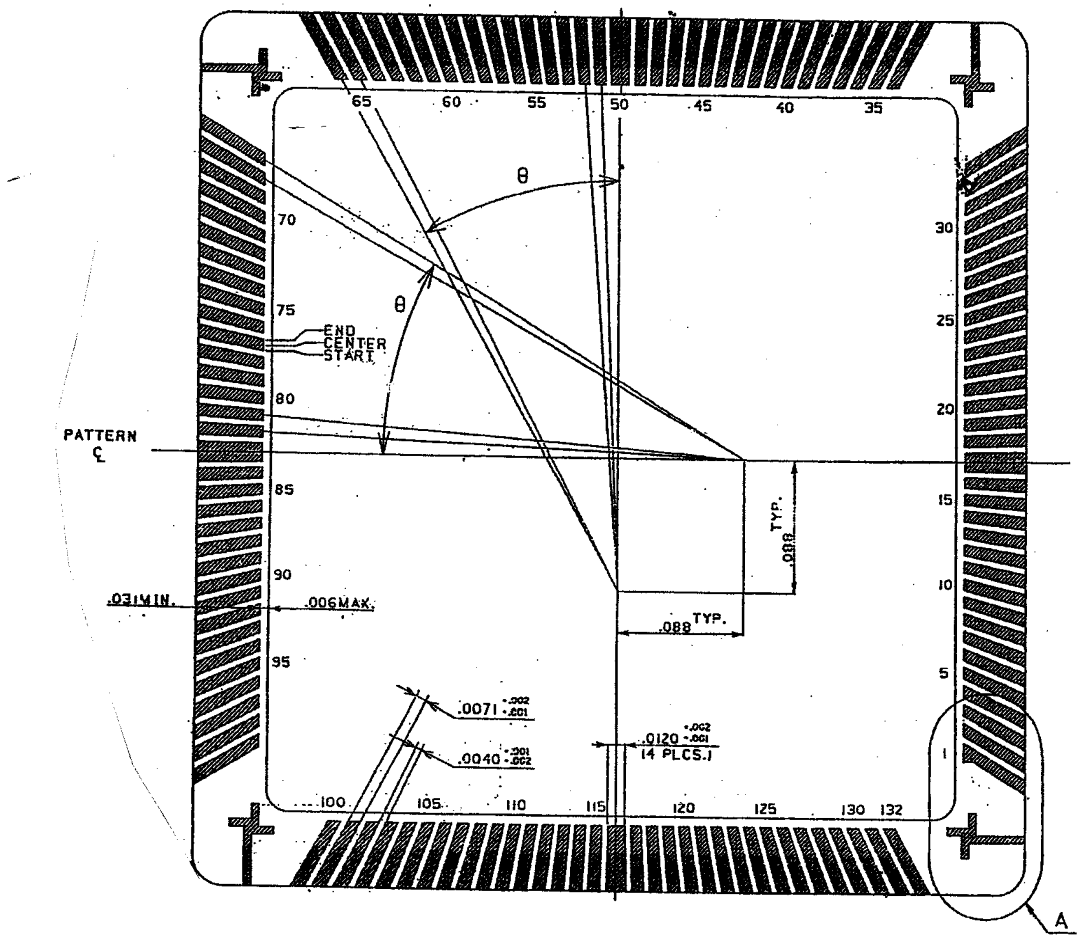
	IN.	MM
.XX±	.01	.01
.XXX±	.005	
ANGLES±	1/4°	

DRAFTER R.J. MENDOZA DATE 2-17-88
ENGINEER DATE
APPROVAL DATE 2-17-88
APPROVAL DATE

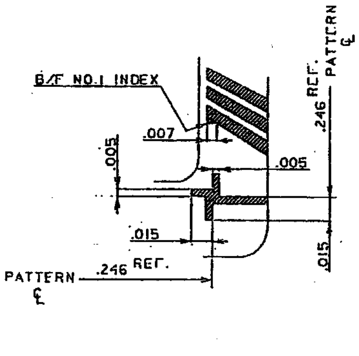
TITLE
132 LD. CERAMIC PGA
(CAVITY UP)
CAVITY: .472

DWG NO.
REV. 1
SCALE
SHT 1 OF 3

SSM P/N CPG13226



B/F ANGLE θ°	B/F EDGES CENTER	START	END	B/F NO.
0.000	0.0000	-0.0060	0.0060	17,50,83,116
2.353	0.0136	0.0101	0.0171	16,18,49,51,82,84,115,117
4.274	0.0247	0.0212	0.0282	15,19,48,52,81,85,114,118
6.191	0.0358	0.0322	0.0394	14,20,47,53,80,86,113,119
8.103	0.0470	0.0434	0.0506	13,21,46,54,79,87,112,120
10.007	0.0582	0.0546	0.0618	12,22,45,55,78,88,111,121
11.900	0.0695	0.0659	0.0731	11,23,44,56,77,89,110,122
13.781	0.0809	0.0773	0.0845	10,24,43,57,76,90,109,123
15.648	0.0924	0.0887	0.0961	9,25,42,58,75,91,108,124
17.499	0.1040	0.1003	0.1077	8,26,41,59,74,92,107,125
19.333	0.1158	0.1121	0.1195	7,27,40,60,73,93,106,126
21.147	0.1276	0.1238	0.1314	6,28,39,61,72,94,105,127
22.940	0.1397	0.1359	0.1435	5,29,38,62,71,95,104,126
24.711	0.1519	0.1480	0.1558	4,30,37,63,70,96,103,129
26.458	0.1642	0.1602	0.1682	3,31,36,64,69,97,102,130
28.179	0.1768	0.1728	0.1808	2,32,35,65,68,98,101,131
29.874	0.1896	0.1855	0.1937	1,33,34,66,67,99,100,132



DETAIL - A

UNLESS OTHERWISE SPECIFIED
DIMENSIONAL TOLERANCES

	in.	mm
.XX ±	.01	.01
.XXX ±	.005	
ANGLES ±	1/2°	

DRAFTER R.J. MENDOZA DATE 2-17-88
ENGINEER DATE
APPROVAL DATE
APPROVAL DATE

TITLE 132 LD. CERAMIC PGA
(CAVITY UP)
CAVITY: .472
DWG NO.
REV. 1
SCALE
SHT 2 OF 3

SSM P/N CPG13226

WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.
1	C3	27	L2	53	P9	79	J14	105	B11
2	B1	28	K3	54	N9	80	H14	106	A11
3	C2	29	N1	55	M9	81	H13	107	C10
4	D3	30	M2	56	P10	82	H12	108	B10
5	C1	31	L3	57	P11	83	G12	109	A10
6	D2	32	P1	58	N10	84	G13	110	C9
7	D1	33	N2	59	P12	85	G14	111	B9
8	E3	34	M3	60	N11	86	F14	112	A9
9	E2	35	P2	61	M10	87	F13	113	A8
10	E1	36	N3	62	P13	88	F12	114	B8
11	F3	37	M4	63	N12	89	E14	115	C8
12	F2	38	P3	64	M11	90	D14	116	C7
13	F1	39	N4	65	P14	91	E13	117	B7
14	G1	40	P4	66	N13	92	C14	118	A7
15	G2	41	M5	67	M12	93	D13	119	A6
16	G3	42	N5	68	N14	94	E12	120	B6
17	H3	43	P5	69	M13	95	B14	121	C6
18	H2	44	M6	70	L12	96	C13	122	A5
19	H1	45	N6	71	M14	97	D12	123	A4
20	J1	46	P6	72	L13	98	A14	124	B5
21	J2	47	P7	73	L14	99	B13	125	A3
22	J3	48	N7	74	K12	100	C12	126	B4
23	K1	49	M7	75	K13	101	A13	127	C5
24	L1	50	M8	76	K14	102	B12	128	A2
25	K2	51	N8	77	J12	103	C11	129	B3
26	M1	52	P8	78	J13	104	A12	130	C4

W/B NO.	PIN NO.
131	A1
132	B2

S/R	NC
D/A	NC

UNLESS OTHERWISE SPECIFIED
DIMENSIONAL TOLERANCES

	in.	mm
.XX±	.01	.01
.XXX±	.005	
ANGLES±	1/4°	

DRAFTER R.J. MENDOZA DATE 2-17-88
ENGINEER DATE
APPROVAL DATE 4/17/88
APPROVAL DATE

TITLE 132 LD. CERAMIC PGA
(CAVITY UP)
CAVITY: .472

DWG NO.
REV. 1
SCALE
SHT 3 OF 5

SPECTRUM
SEMICONDUCTOR MATERIALS, INC.